

MURHD560T4G, SURHD8560T4G, MURHD560W1T4G, SURHD8560W1T4G



Power Rectifier

Features and Benefits

- Ultrafast 30 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 Volts
- AEC-Q101 Qualified and PPAP Capable
- SURHD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These are Pb-Free Devices*

Applications

- Power Supplies
- Inverters
- Free Wheeling Diodes

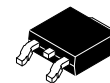
Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 0.4 g (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
 - ◆ Machine Model = C (> 400 V)
 - ◆ Human Body Model = 3B (> 8000 V)

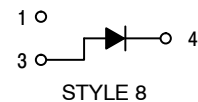
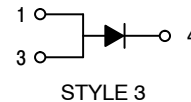
ON Semiconductor®

<http://onsemi.com>

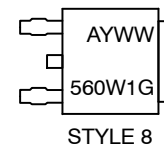
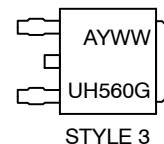
**ULTRAFAST RECTIFIER
5.0 AMPERES
600 VOLTS**



**DPAK
CASE 369C
STYLES 3, 8**



MARKING DIAGRAMS



UH560 = MURHD560T4
560W1 = MURHD560W1T4
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping†
MURHD560T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SURHD8560T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
MURHD560W1T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SURHD8560W1T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	600	V
Average Rectified Forward Current (Rated V_R , $T_C = 159^\circ\text{C}$)	$I_{F(AV)}$	5.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	50	A
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-65 to +175	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.5	$^\circ\text{C/W}$
Maximum Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	49.5	$^\circ\text{C/W}$

1. Rating applies when surface mounted on a 1.5 mm FR4 PC board with a 1 oz. thick, 700 mm² Cu area.

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) ($I_F = 5.0$ Amps, $T_C = 25^\circ\text{C}$) ($I_F = 5.0$ Amps, $T_C = 125^\circ\text{C}$)	V_F	2.7 1.65	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = 25^\circ\text{C}$) (Rated dc Voltage, $T_C = 125^\circ\text{C}$)	I_R	10 70	μA
Maximum Reverse Recovery Time ($I_F = 1.0$ Amp, $di/dt = 50$ Amps/ μs , $V_R = 30$ V, $T_J = 25^\circ\text{C}$)	t_{rr}	30	ns

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

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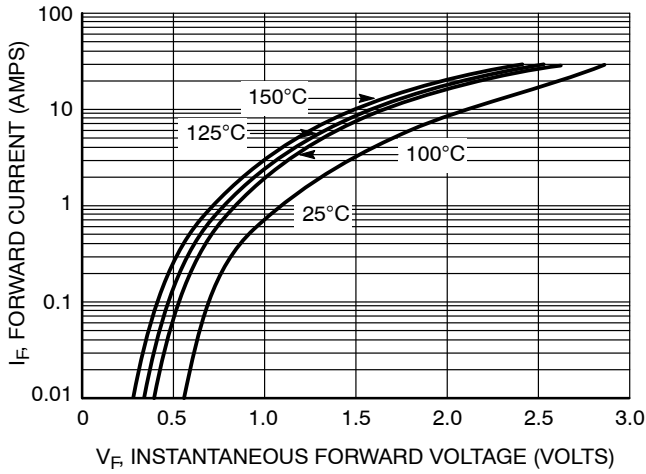


Figure 1. Typical Forward Voltage

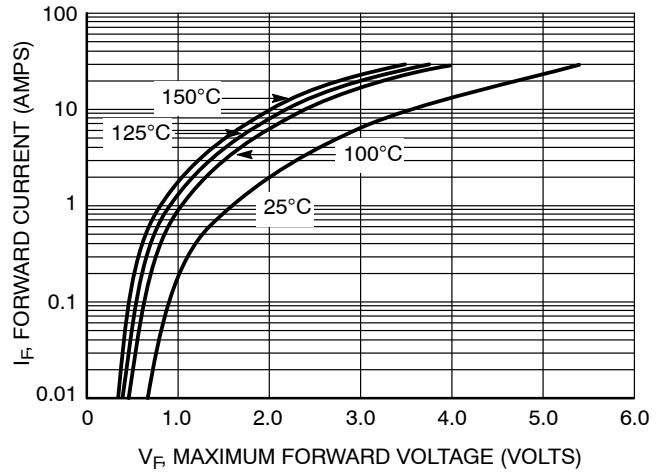


Figure 2. Maximum Forward Voltage

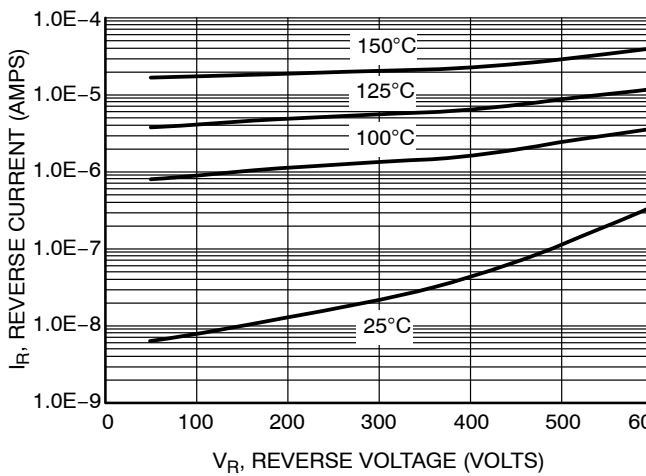


Figure 3. Typical Reverse Current

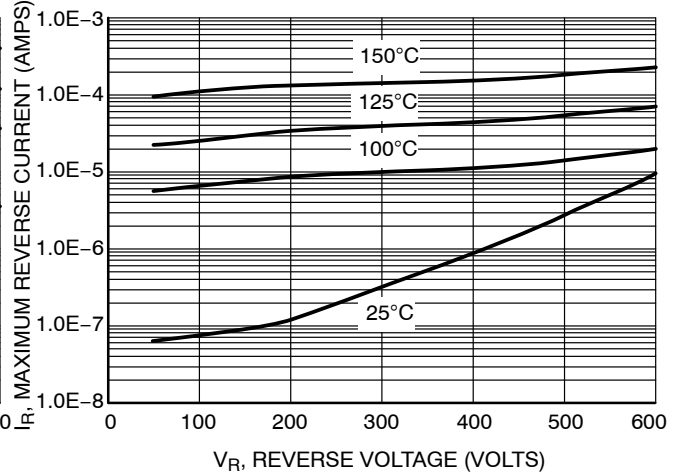


Figure 4. Maximum Reverse Current

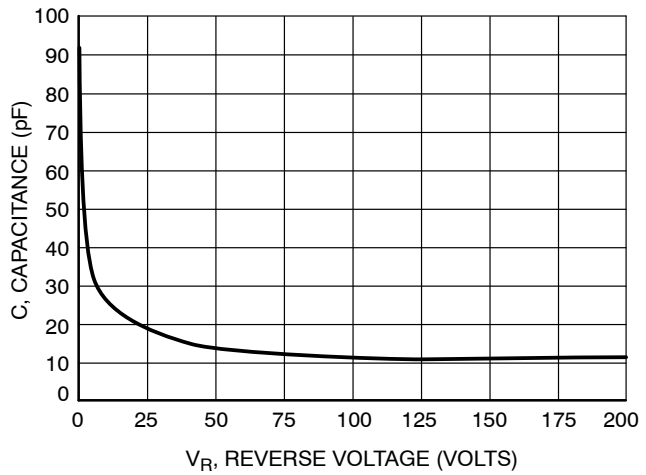


Figure 5. Typical Capacitance

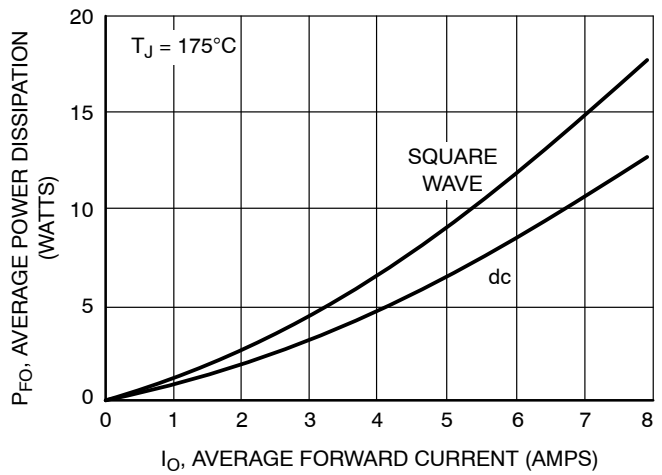


Figure 6. Forward Power Dissipation

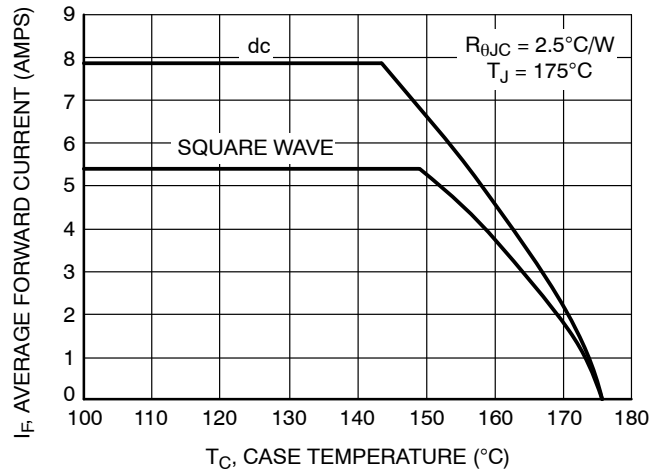


Figure 7. Current Derating

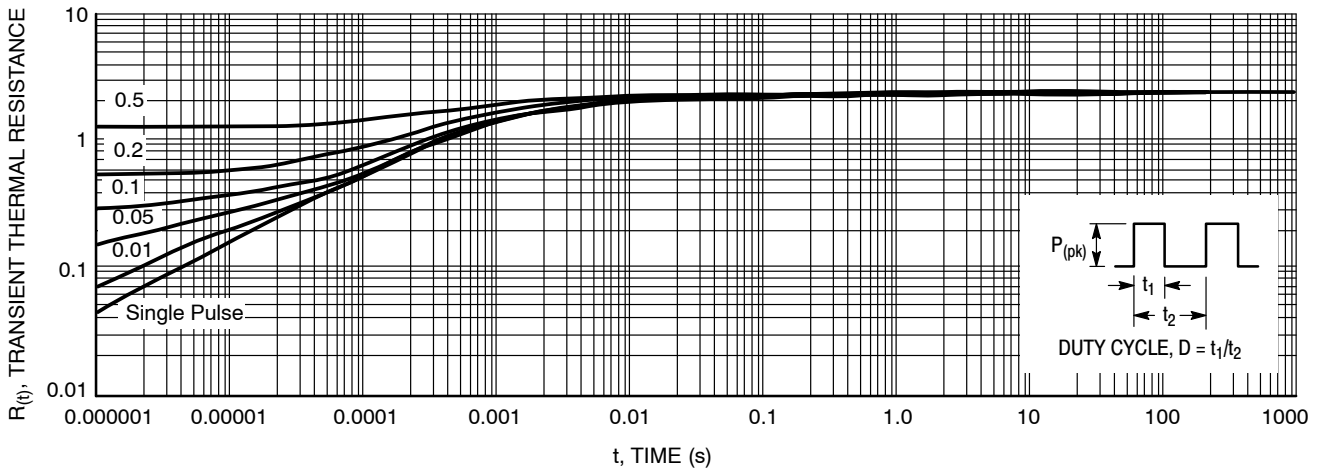


Figure 8. Thermal Response, Junction to Case

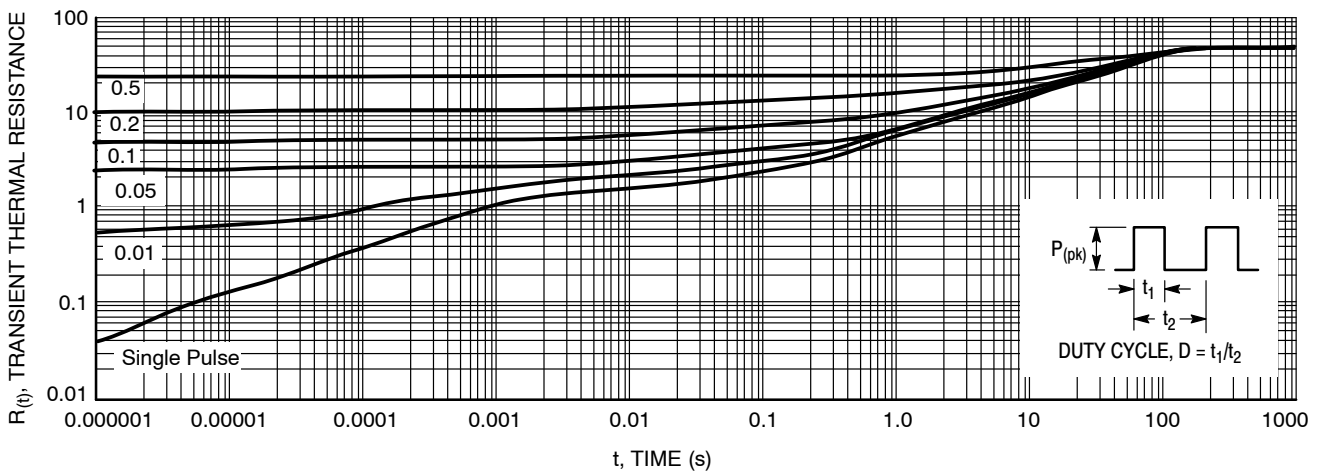
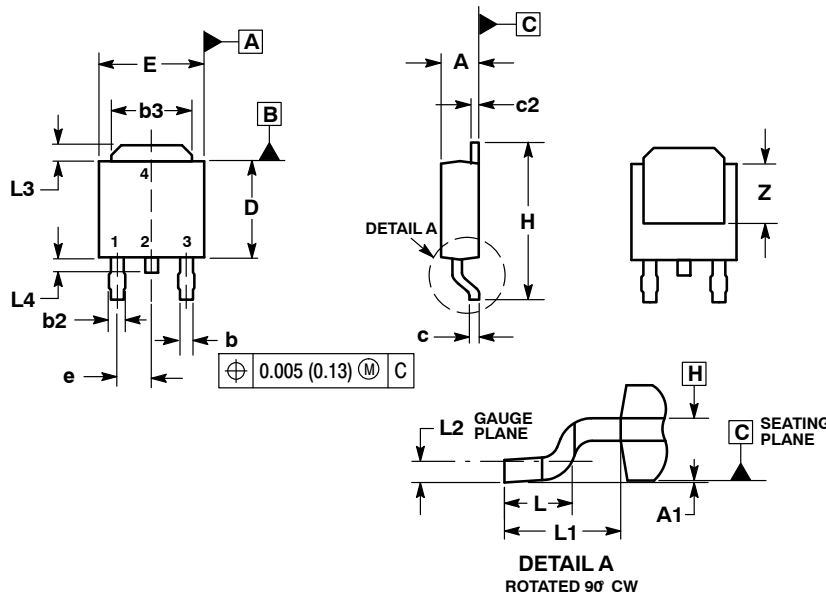


Figure 9. Thermal Response, Junction to Ambient

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PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369C-01 ISSUE D

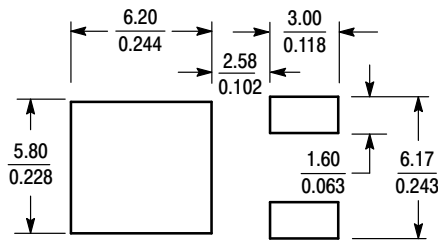


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



SCALE 3:1 (mm/inches)

STYLE 3:

- PIN 1. ANODE
- CATHODE
- ANODE
- CATHODE

STYLE 8:

- PIN 1. N/C
- CATHODE
- ANODE
- CATHODE

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